Erratum to: Comparative analysis of a wood-adhesive bondline

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The original version of this article contains a mistake. The presentation of this title was incorrect (colon instead of hyphen). The correct title should read:

Comparative analysis of a wood-adhesive bondline

The online version of the original article can be found under doi:[10.1007/s00226-010-0304-z](https://doi.org/10.1007/s00226-010-0304-z).

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